

MA2YF80

Silicon epitaxial planar type

For high speed switching circuits
 For strobe light circuits (high voltage rectification)

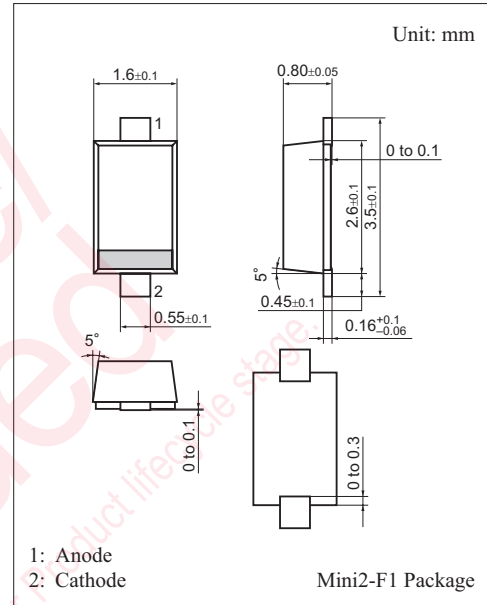
■ Features

- High repetitive peak reverse voltage V_{RRM}
- Short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	800	V
Non-repetitive peak reverse surge voltage	V_{RSM}	800	V
Forward current	I_F	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



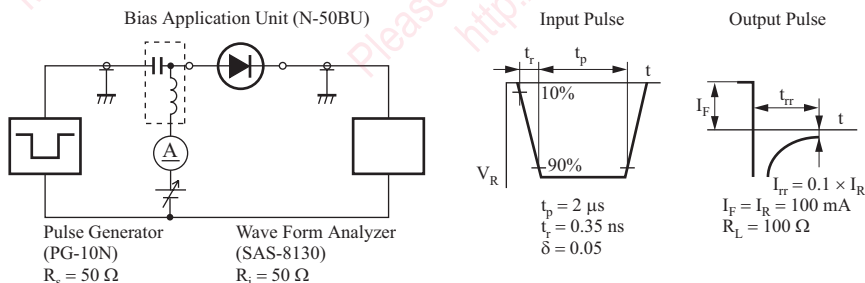
Marking Symbol: HB

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			2.5	V
Reverse current	I_{RRM1}	$V_{RRM} = 400 \text{ V}$			1	μA
	I_{RRM2}	$V_{RRM} = 800 \text{ V}$			20	
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *	t_{rr}	$I_F = 100 \text{ mA}, I_R = 200 \text{ mA}$ $I_{rr} = 20 \text{ mA}, R_L = 100 \Omega$		20	45	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. *: t_{rr} measurement circuit



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